	Туре	L#	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	128	Metal with bump with die		2002/11/20 09:54
2	BRS	L2	0	1 and (bump with bind\$3 with finger with leadframe)	USPAT; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:57
3	BRS	L3	0	bump with bind\$3 with finger with leadframe	USPAT; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:18
4	BRS	L4	0	bind\$3 with finger with leadframe	USPAT; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:19
5	BRS	L5	133	finger with leadframe	USPAT; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:58
6	BRS	L6	0	1 and 5	USPAT; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 09:19

			Hits	T	Search Text	DBs USPA		e Stamp
+	Type	L# 	L # Hits				O; 2002/11/20 09:21 ;	
	BRS	L8	548	4	Metal with bump	USP.; EPO JPO DEF ENT IBM DB	O; 200 kW 09: f;)2/11/20 55
9	BRS	LS	9 0		8 and (bump with bind\$3 wifinger with leadframe)	; EI JP(DE EN IB DI	D; 20 RW 09 IT; M_T	002/11/20 9:57
10	BRS	5 I	_10)	8 and (bind\$3 with finger v leadframe)	vith ; I Vith D E II I	ERW NT; BM_T)B	2002/11/20 09:58
	1 BF	RS	L11	3	8 and (finger with leadfra	me)	JSPAT EPO; IPO; DERW ENT; IBM_T DB USPA	2002/11/20 10:00
	12 E	BRS	L12	3	11 and heat\$3		; EPO; JPO; DERV ENT; IBM_ DB	V 2002/11/20 10:01

				, [Search Text			Time Stamp
BR		L# \	Hit		ıd press\$3	; E JPO DE EN	ERW 1 NT; M_T	2002/11/20 12:07
4 15	S&R	L14	2	("52	52853").PN.	;] JI E I I	ERW NT; BM_T OB	2002/11/20 14:46
15	BRS	L15	5 1	flij	o with leadframe with	n package	IBM_ DB	7 2002/11/20 14:50
16	BRS	L	16	3	5 and heat\$3 and pre	ess\$3	USPA; EPC JPO; DER ENT IBM DB	2002/11/20 W 14:54 ;_T
17	BRS	5	<u></u>	1	16 and bump		DB	O; RW 14:53 T; M_T
13	8 BF	≀S	L18	614685	flip chip interconne	ction	; E JP DI EN	PO; O; ERW 14:53 NT; M_T

	Туре	L#	Hits	Search Text	DBs	Time Stamp
19	BRS	L19	733	flip with chip with interconnection	USPAT; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:53
20	BRS	L20	315	19 and heat\$3 and press\$3	USPAT; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:54
21	BRS	L21	184	19 and heat\$3 and press\$3 and bump	USPAT; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:55
22	BRS	L22	83	21 and (temperature same pressure)	USPAT; EPO; JPO; DERW ENT; IBM_T DB	2002/11/20 14:55